

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Jian-Bin Shiu</td> <td>04/11/2012</td> </tr> <tr> <td>Tung-Sheng Lee</td> <td>04/11/2012</td> </tr> </tbody> </table>		Name	Execution Date	Jian-Bin Shiu	04/11/2012	Tung-Sheng Lee	04/11/2012		
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RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>UNITED MICROELECTRONICS CORP.</td> </tr> <tr> <td>Street Address:</td> <td>No.3, Li-Hsin Road 2, Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu City</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> </table>		Name:	UNITED MICROELECTRONICS CORP.	Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	City:	Hsin-Chu City	State/Country:	TAIWAN
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PROPERTY NUMBERS Total: 1									
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CORRESPONDENCE DATA									
<p>Fax Number: (703)997-4517</p> <p>Phone: 3027291562</p> <p>Email: Patent.admin.uspto.cr@naipo.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: WINSTON HSU</p> <p>Address Line 1: P.O.BOX 506</p> <p>Address Line 4: Merrifield, VIRGINIA 22116</p>									
ATTORNEY DOCKET NUMBER:	NAUP1444USA								
NAME OF SUBMITTER:	SIBYL YU								
<p>Total Attachments: 2</p> <p>source=1350120#page1.tif</p> <p>source=1350120#page2.tif</p>									

CH \$40.00 13445934

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNOR(S) (Inventors):

Name: Jian-Bin Shiu Nationality: TW

Name: Tung-Sheng Lee Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: UNITED MICROELECTRONICS CORP.

Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"TEST STRUCTURE FOR SEMICONDUCTOR PROCESS AND METHOD FOR
MONITORING SEMICONDUCTOR PROCESS"**

Which is found in :

- (a) + U.S. patent application executed on even date
(b) _____ U.S. patent application executed on _____
(c) _____ U.S. application serial no. _____
(d) _____ patent no. _____ issued _____
(e) _____ International application no. _____

PATENT

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this APR 11 2012 (Date of signing). (請註明人務必簽署上列日期。)

(Type name of inventor)

Jian-Bin Shiu

Tung-Sheng Lee

Signature of INVENTOR

Jian-Bin Shiu

Tung Sheng Lee

PATENT